

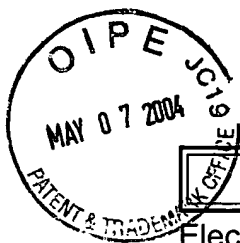
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Electronic Patent Application Submission
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EFS ID: 60599
Application ID: 10763859
Title of Invention: SEMICONDUCTOR PACKAGE
HAVING REDUCED THICKNESS
First Named Inventor: TAE LEE
Domestic/Foreign Application: Domestic Application
Filing Date: 2004-01-23
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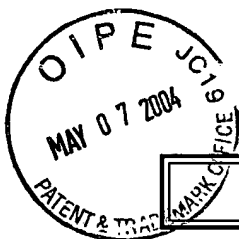


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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids1-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids1-usidst.xml		us-ids.dtd		us-ids.xsl
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	us-ids.dtd									
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Electronic Version v18

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<h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>2596993</td><td>1952-05-20</td><td>S.L. Gookin</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>3435815</td><td>1969-04-01</td><td>Forcier</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>3734660</td><td>1973-05-22</td><td>Davies et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>3838984</td><td>1974-10-01</td><td>Crane et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>4054238</td><td>1977-10-18</td><td>Lloyd et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>6</td><td>4189342</td><td>1980-02-19</td><td>Kock</td><td></td><td></td><td></td></tr><tr><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></tr></tbody></table>							init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	2596993	1952-05-20	S.L. Gookin					2	3435815	1969-04-01	Forcier					3	3734660	1973-05-22	Davies et al.					4	3838984	1974-10-01	Crane et al.					5	4054238	1977-10-18	Lloyd et al.					6	4189342	1980-02-19	Kock											
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Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
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	8	20020163015	2002-11-07	LEE ET AL.			
	9	20030030131	2003-02-13	LEE ET AL.			
	10	20030073265	2003-04-17	HU ET AL.			

Signature

Examiner Name	Date